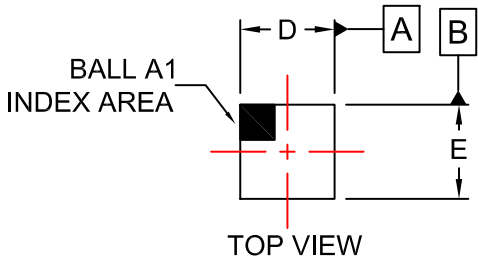




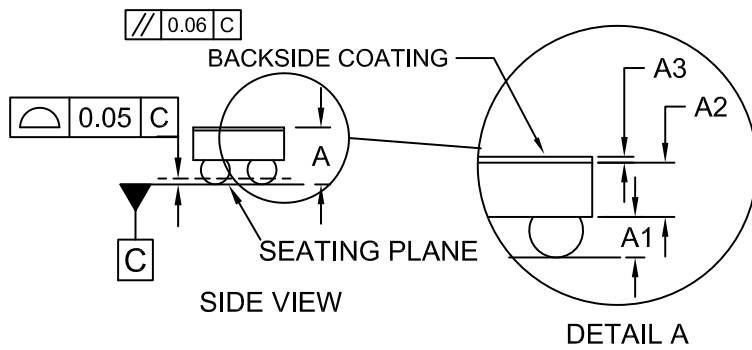
WLCSP4 0.70x0.70x0.454
CASE 567ZV
ISSUE O

DATE 17 DEC 2020

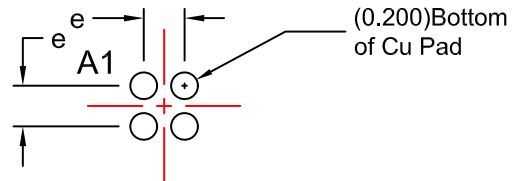
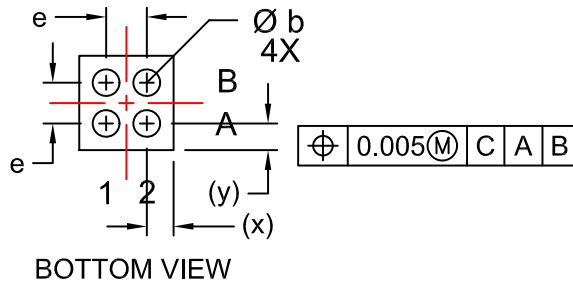


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DATUM C APPLIES TO THE SPHERICAL CROWN OF THE SOLDER BALLS



DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.413	0.454	0.495
A1	0.154	0.174	0.194
A2	0.237	0.255	0.273
A3	0.022	0.025	0.028
b	0.210	0.230	0.250
D	0.67	0.7	0.73
E	0.67	0.7	0.73
e	0.35 BSC		
x	0.160	0.175	0.190
y	0.160	0.175	0.190



GENERIC MARKING DIAGRAM*



- X = Specific Device Code
- M = Date Code

RECOMMENDED MOUNTING FOOTPRINT* (NSMD PAD TYPE)

*FOR ADDITIONAL INFORMATION ON OUR Pb-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

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DESCRIPTION:	WLCSP4 0.70x0.70x0.454	PAGE 1 OF 1

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